

Product / Package Information

Package	QSOP_EP - GaAs
Body Size	
Lead Count	16
Terminal Finish	100Sn
MS Number	MS012612C

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.91 E-02	86.91	869100	38.64	386365
Thermosets	Epoxy & Phenol Resin	Proprietary	7.22 E-03	12.78	127800	5.68	56815
Other inorganic materials	Carbon black	1333-86-4	1.75 E-04	0.31	3100	0.14	1378
Subtotal			5.65 E-02	100.00	1000000	44.46	444558

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.10 E-02	97.50	975000	32.30	323013
Copper & its alloys	Iron	7439-89-6	9.89 E-04	2.35	23500	0.78	7785
Copper & its alloys	Zinc	7440-66-6	5.05 E-05	0.12	1200	0.04	398
Copper & its alloys	Phosphorus	7723-14-0	1.26 E-05	0.03	300	0.01	99
Subtotal			4.21 E-02	100.00	1000000	33.13	331295

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.34 E-03	100.00	1000000	2.63	26283

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	8.38 E-04	99.99	1000000	0.66	6596

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Gallium Arsenide	1303-00-0	3.35 E-03	100.0	1000000	2.63	26336

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.13 E-03	84.50	845000	2.46	24637
Other organic materials	Solvent	Propriety	5.56 E-04	15.00	150000	0.44	4373
Other organic materials	Epoxy Resin	Propriety	1.85 E-05	0.50	5000	0.01	146
Subtotal			3.70 E-03	100.00	1000000	2.92	29156

Copper Slug

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.72 E-02	100.0	5155557	13.58	135776

Package Totals	Weight (g)	Percentage (%)	PPM
	1.27 E-01	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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